

AZ ECI 3012 – run sheet

Merck

[nanyte.com/photolithography/photoresists/az-eci-3012](https://www.merck.com/photolithography/photoresists/az-eci-3012) · last updated 2026-07-26

Thickness: 1.1–1.9 μm

Softbake: 90 °C · 1.5 min · hotplate

Exposure dose: 220 mJ/cm² @ 436 nm

Post-exposure bake: 110 °C

Develop: Developer AZ 300MIF · Dilution used as supplied (ready-to-use MIF developer) · Time 60 s · Method puddle

Hardbake: 100–115 °C